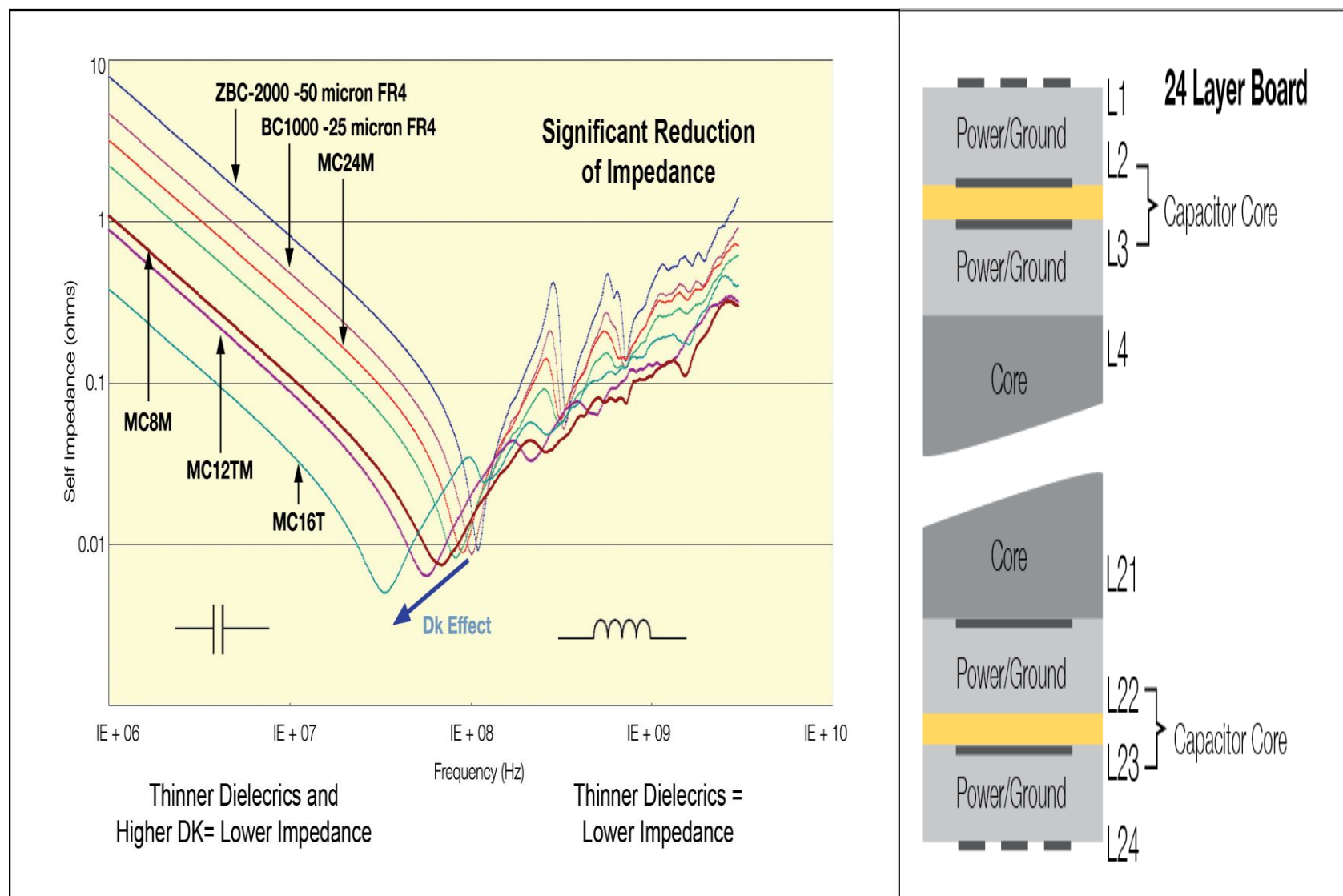
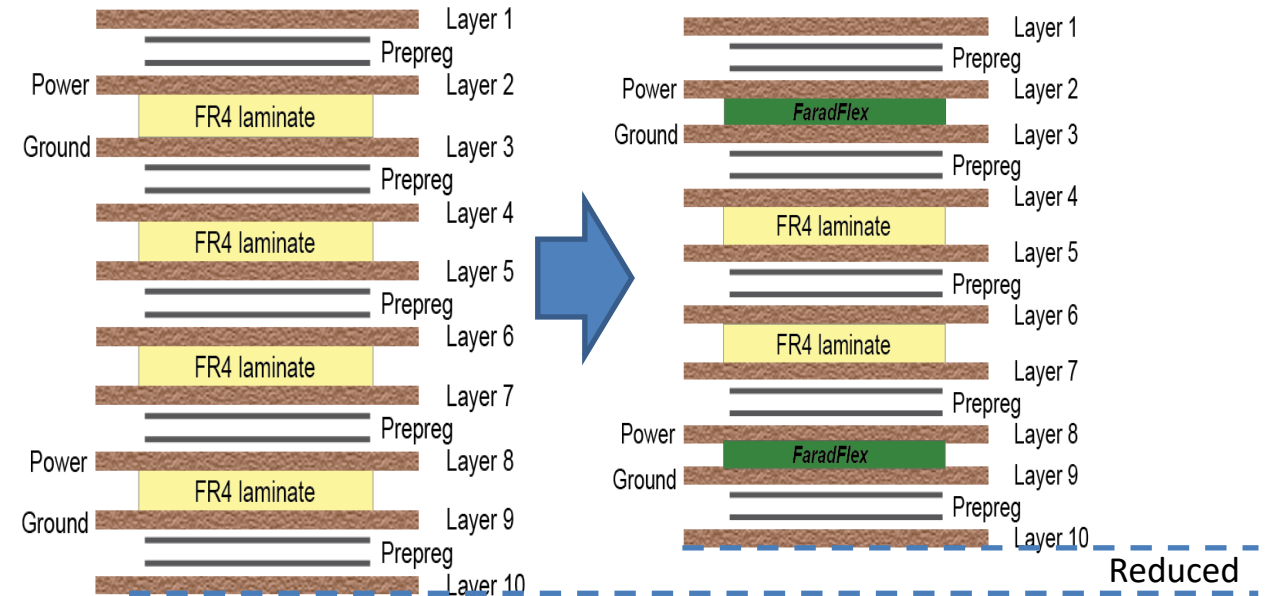
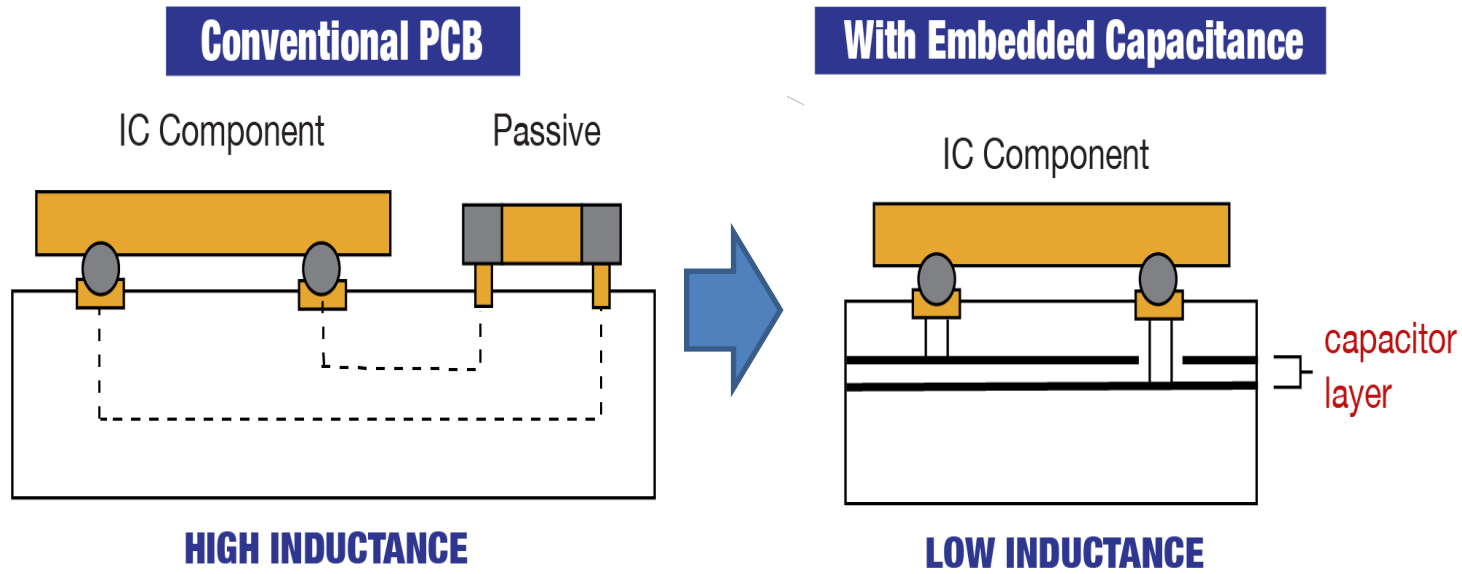




使用 FaradFlex™ 將電容器嵌入電路板降低訊號干擾、減少PCB板厚

FaradFlex™ reduces power buss noise, need for decoupling capacitors, and PCB thickness



FaradFlex™ 的優點及特性

FaradFlex™ Benefits & Property

- 減少PCB板厚 - Reduce PCB thickness
- 減少阻抗 - Reduce impedance
- 降低EMI干擾 - Minimize EMI noise
- 改善訊號品質 - Improve Signal Integrity
- 提升性能 - Increase functionality
- 絕緣層厚度 - Dielectric thickness: 2 - 25 μm
- 電容 - Capacitance: 0.9 nF/in² to 50 nF/in²
- 介電常數 - Dk: 3.8 to 30
- 損耗因子 - Df: 0.0015 - 0.021 at 10GHz

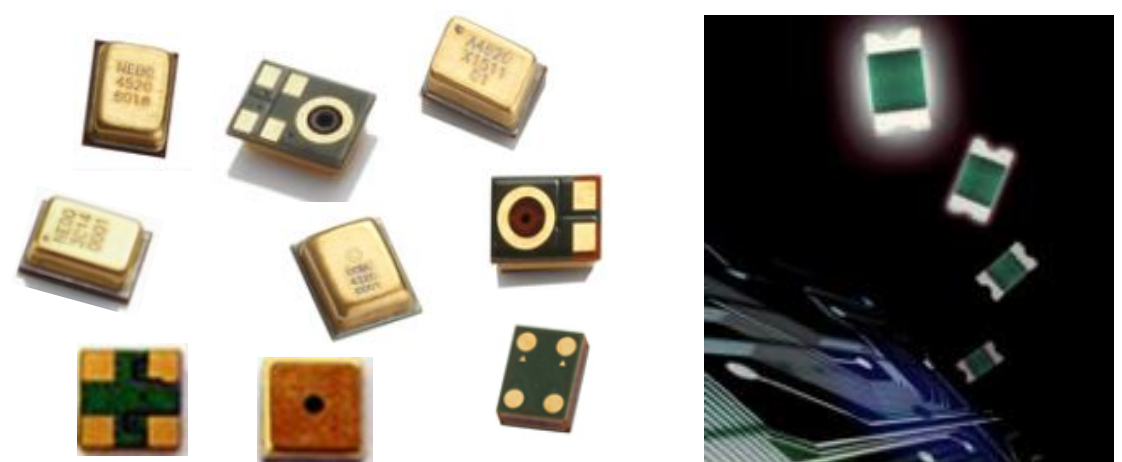
FaradFlex™

FaradFlex™ in Router, Server, infrastructure applications



FaradFlex™ 可應用於 MEMS、模組、感測器等

FaradFlex™ in MEMS, modules and sensor applications



	MC24M	MC12M	MC8M	MC12TM
Thickness (μm)	24	12	8	12
Cp@1MHz (nF/in ²)	1.2	2.0	3.1	4.2
DK@1MHz	4.4	4.4	4.4	10
Df@1MHz	0.015	0.015	0.015	0.015
Peels (lbs/in)	5	5	5	4

	MC8TM	MC12TB	MC6TB	MC3TB	MC12LD
Thickness (μm)	8	12	6	3	12
Cp@1kHz (nF/in ²)	7	10	20	40	4.5
DK@1MHz	10.5	21.7	21.7	21.7	7.5
Df@1MHz	0.02	0.008	0.008	0.008	0.002
Peels (lbs/in)	4	4	4	4	4

